BT132-600D

4Q Triac

Rev.03 - 26 July 2023 Product data sheet

1. General description

Planar passivated very sensitive gate four quadrant triac in a TO92 plastic package intended for use in general purpose bidirectional switching and phase control applications. This very sensitive gate "series D" triac is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

2. Features and benefits

- High blocking voltage capability
- Very sensitive gate
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drivers and microcontrollers
- Enhanced current surge capability

3. Applications

- Battery powered applications
- General purpose switching and phase control
- Air conditioner indoor fan control

4. Quick reference data

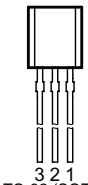
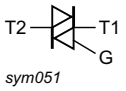
Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V_{DRM}	repetitive peak off-state voltage		600				V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{lead} \leq 51$ °C; Fig. 1; Fig. 2; Fig. 3	1				A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25$ °C; $t_p = 20$ ms; Fig. 4; Fig. 5	16				A
		full sine wave; $T_{j(init)} = 25$ °C; $t_p = 16.7$ ms	17.5				A
T_j	junction temperature		125				°C
Symbol	**Parameter**	**Conditions**		**Min**	**Typ**	**Max**	**Unit**
Static characteristics							
I_{GT}	gate trigger current	$V_D = 12$ V; $I_T = 0.1$ A; T2+ G+; $T_j = 25$ °C; Fig. 7		-	2	5	mA
		$V_D = 12$ V; $I_T = 0.1$ A; T2+ G-; $T_j = 25$ °C; Fig. 7		-	2.5	5	mA
		$V_D = 12$ V; $I_T = 0.1$ A; T2- G-; $T_j = 25$ °C; Fig. 7		-	2.5	5	mA
		$V_D = 12$ V; $I_T = 0.1$ A; T2- G+; $T_j = 25$ °C; Fig. 7		-	5	10	mA
I_H	holding current	$V_D = 12$ V; $T_j = 25$ °C; Fig. 9		-	1.2	10	mA
V_T	on-state voltage	$I_T = 5$ A; $T_j = 25$ °C; Fig. 10		-	1.4	1.7	V

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; $R_{GT1(ext)}$ = 1 kΩ		-	5	-	V/µs

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T2	main terminal 2	 3 2 1 TO-92 (SOT54)	 sym051
2	G	gate		
3	T1	main terminal 1		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BT132-600D	TO92	BT132-600D,412	Bulk	1000	SOT54	14-Nov-2013
BT132-600D	TO92	BT132-600D,116	Reel	2000	SOT54 wide pitch	14-Nov-2013

7. Marking

Table 4. Marking codes

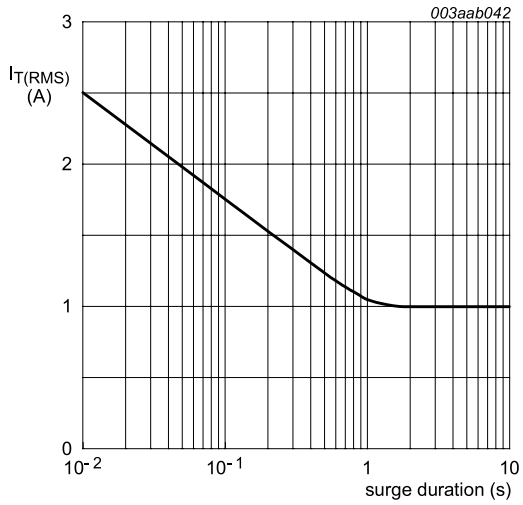
Type number	Marking codes
BT132-600D	132-6D

8. Limiting values

Table 5. Limiting values

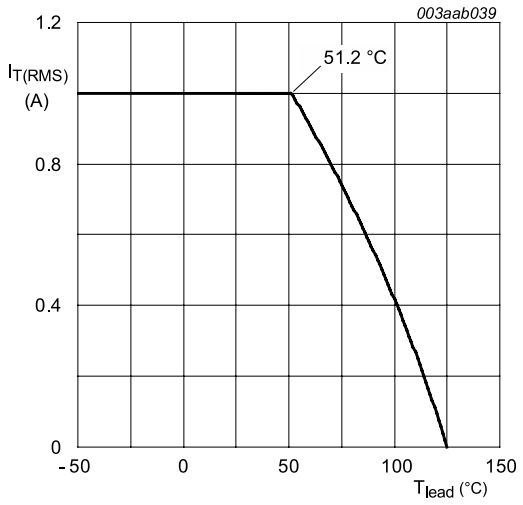
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{lead} \leq 51$ °C; Fig 1; Fig 2; Fig 3	1	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25$ °C; $t_p = 20$ ms; Fig 4; Fig 5	16	A
		full sine wave; $T_{j(init)} = 25$ °C; $t_p = 16.7$ ms	17.5	A
I^2t	I^2t for fusing	$t_p = 10$ ms; SIN	1.28	A^2s
dI_T/dt	rate of rise of on-state current	$I_G = 10$ mA	50	A/µs
		$I_G = 10$ mA	50	A/µs
		$I_G = 10$ mA	50	A/µs
		$I_G = 20$ mA	10	A/µs
I_{GM}	peak gate current		2	A
P_{GM}	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T_{stg}	storage temperature		-40 to 150	°C
T_j	junction temperature		125	°C



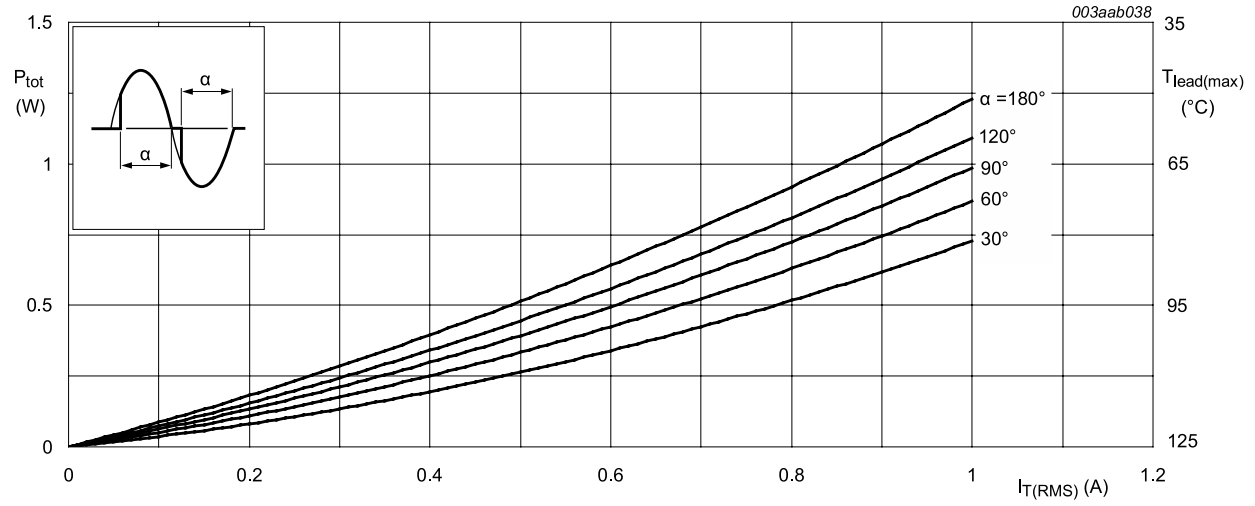
f = 50 Hz; T_{lead} = 51.2 °C

Fig. 1. RMS on-state current as a function of surge duration; maximum values



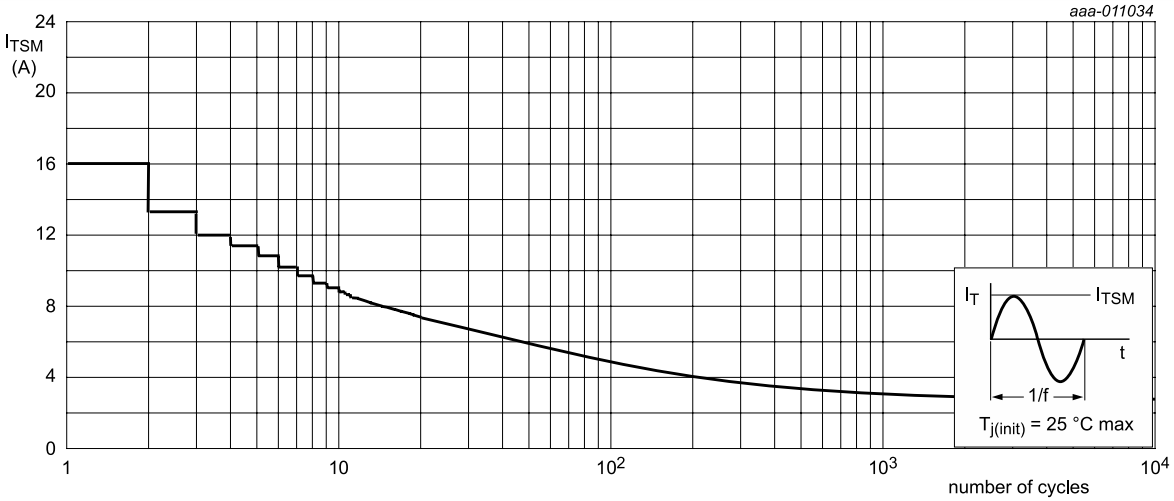
T_{lead} = 51.2 °C

Fig. 2. RMS on-state current as a function of lead temperature; maximum values



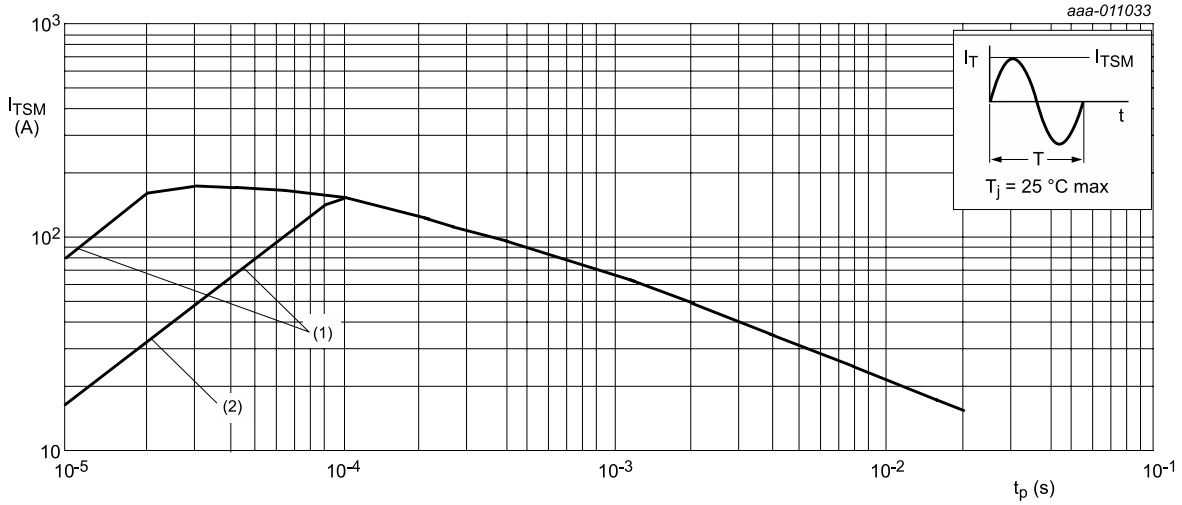
α = conduction angle

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



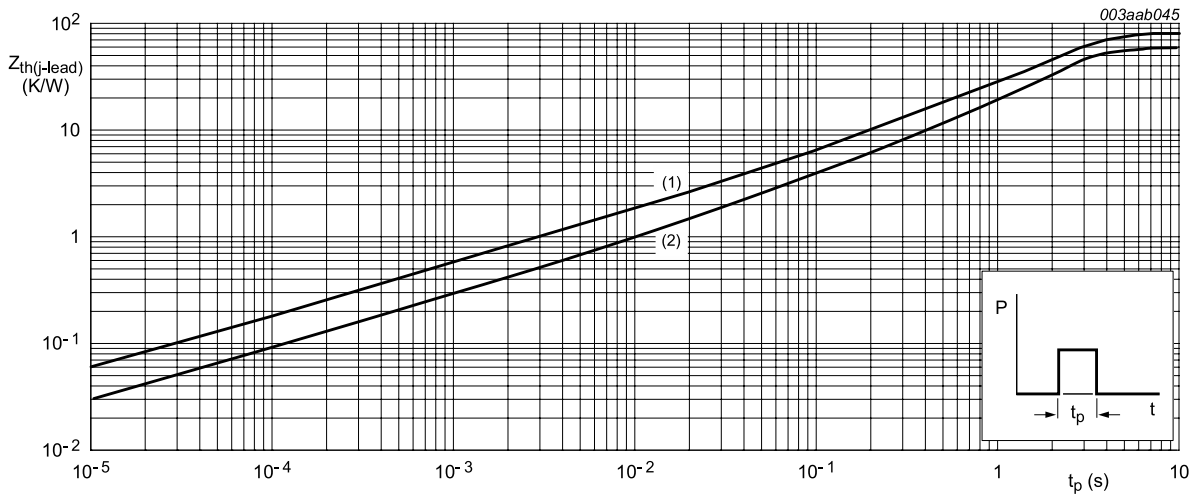
$t_p \leq 20$ ms
(1) dI_T/dt limit
(2) T2- G+ quadrant limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j\text{-}lead)}$	thermal resistance from junction to lead	full cycle; Fig 6		-	-	60	K/W
		half cycle; Fig 6		-	-	80	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient free air	printed circuit mounted: lead length = 4 mm		-	150	-	K/W



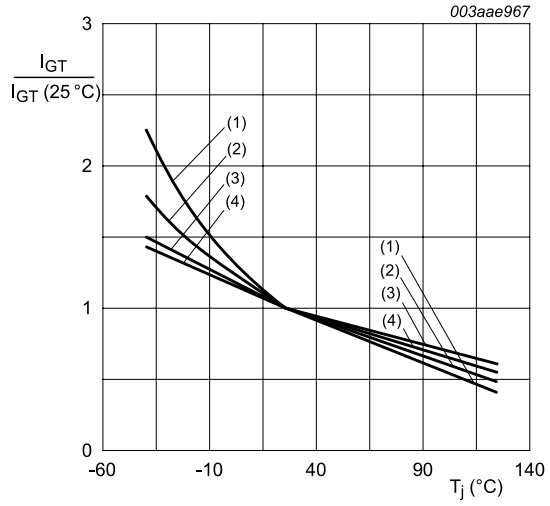
(1) Unidirectional (half cycle)
(2) Bidirectional (full cycle)

Fig. 6. Transient thermal impedance from junction to lead as a function of pulse width

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T2+ G+; T_j = 25 °C; Fig. 7		-	2	5	mA
		V_D = 12 V; I_T = 0.1 A; T2+ G-; T_j = 25 °C; Fig. 7		-	2.5	5	mA
		V_D = 12 V; I_T = 0.1 A; T2- G-; T_j = 25 °C; Fig. 7		-	2.5	5	mA
		V_D = 12 V; I_T = 0.1 A; T2- G+; T_j = 25 °C; Fig. 7		-	5	10	mA
I_L	latching current	V_D = 12 V; I_G = 0.1 A; T2+ G+; T_j = 25 °C; Fig. 8		-	1.6	10	mA
		V_D = 12 V; I_G = 0.1 A; T2+ G-; T_j = 25 °C; Fig. 8		-	4.5	15	mA
		V_D = 12 V; I_G = 0.1 A; T2- G-; T_j = 25 °C; Fig. 8		-	1.2	10	mA
		V_D = 12 V; I_G = 0.1 A; T2- G+; T_j = 25 °C; Fig. 8		-	2.2	15	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; Fig. 9		-	1.2	10	mA
V_T	on-state voltage	I_T = 5 A; T_j = 25 °C; Fig. 10		-	1.4	1.7	V
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 11		-	0.7	1.5	V
		V_D = 400 V; I_T = 0.1 A; T_j = 125 °C		0.25	0.4	-	V
I_D	off-state current	V_D = 600 V; T_j = 125 °C		-	0.1	0.5	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; $R_{GT1(ext)}$ = 1 kΩ		-	5	-	V/µs
t_{gt}	gate-controlled turn-on time	I_{TM} = 6 A; V_D = 600 V; I_G = 0.1 A; dI_G/dt = 5 A/µs		-	2	-	µs



(1) T2- G+
(2) T2- G-
(3) T2+ G-
(4) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

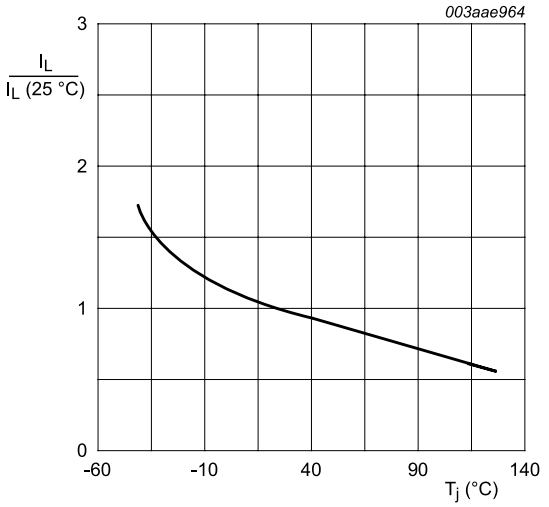


Fig. 8. Normalized latching current as a function of junction temperature

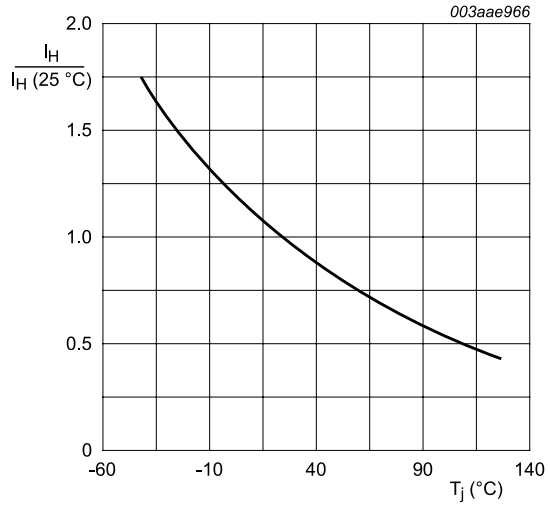
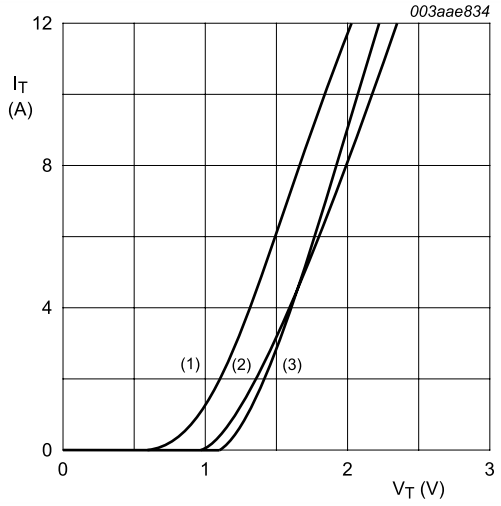


Fig. 9. Normalized holding current as a function of junction temperature



V_o = 1.27 V; R_s = 0.091 Ω
(1) T_j = 125 °C; typical values
(2) T_j = 125 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

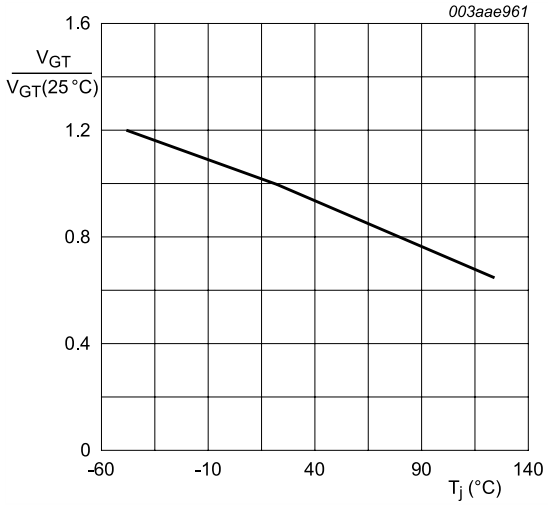
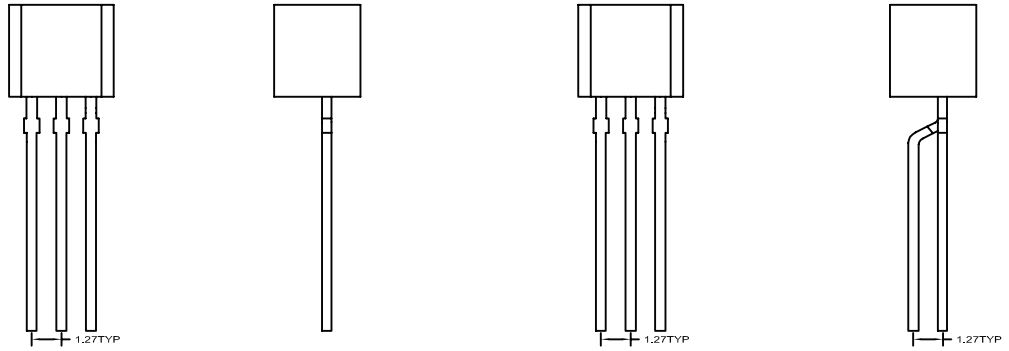


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

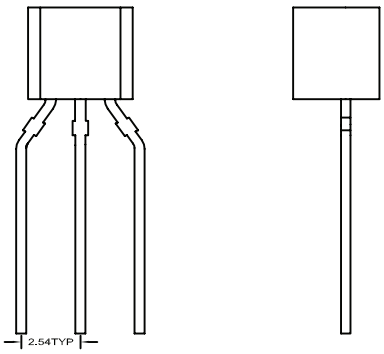
11. Package outline

SOT54 PACKAGE OUTLINE

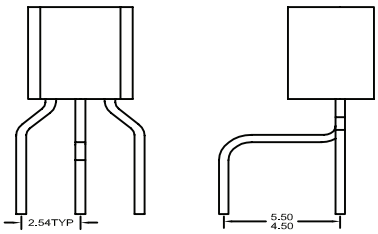


SOT54
Bulk Pack - 412

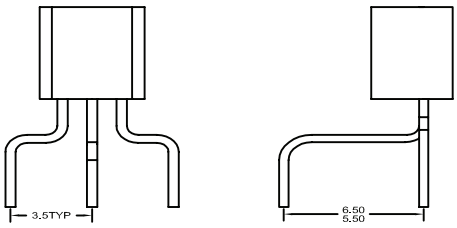
SOT54 LEADS ON CIRCLE
Bulk Pack - 112



SOT54 WIDE PITCH
Tape/ Reel Pack - 116
Ammo Pack - 126



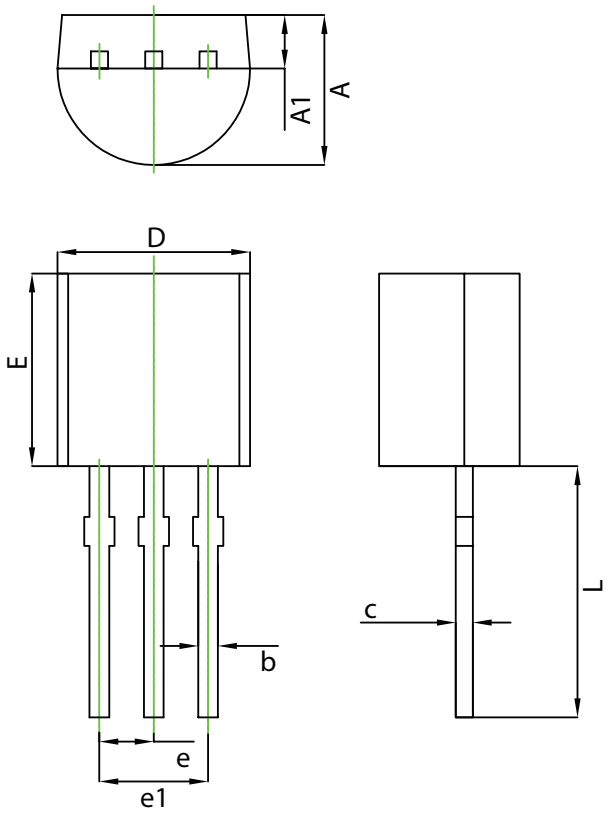
SOT54 LEAD BEND L01
Bulk Pack - 412



SOT54 LEAD BEND L02
Bulk Pack - 412

Remark: Detailed dimensions refer to POD drawing.

Plastic single-ended leaded(through hole) package; 3 leads TO92



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	3.300	3.700	0.130	0.146
A1	1.100	1.400	0.043	0.055
b	0.380	0.550	0.015	0.022
c	0.360	0.510	0.014	0.020
D	4.300	4.700	0.169	0.185
E	4.300	4.700	0.169	0.185
e	1.270 TYP.		0.050 TYP.	
e1	2.440	2.640	0.096	0.104
L	14.100	14.500	0.555	0.571

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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13. Contents

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Date of release: 26 July 2023